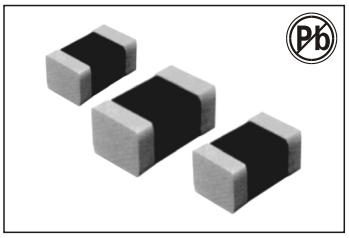


SURFACE–MOUNT MULTI–LAYER CHIP BEADS

FEATURES:

- Multilayer structure
- Closed magnetic circuit
- Avoids crosstalk
- Excellent magnetic shield
- Excellent solderability
- High reliability
- EMI/RFI suppression
- 20%impedance tolerance

COMMON APPLICATIONS:

- Cellular Phones
- Mobil Radios
- Cordless Telephones
- Modems
- Global Positioning Systems
- Wireless Communications Equipment
- Network Systems
- Computer Products

ELECTRICAL CHARACTERISTICS:

IMPEDANCE Ω AT 100 MHz	DCR (Ω) Max	IDC Max mA
7	0.20	600
11	0.20	600
19	0.20	600
26	0.20	400
31	0.20	400
36	0.20	400
60	0.25	400
70	0.25	400
80	0.25	400
100	0.25	400
120	0.25	300
150	0.25	300
180	0.25	300
220	0.25	300
300	0.25	300
500	0.35	200
600	0.40	200
800	0.40	150
1000	0.45	100
1200	0.06	100
1500	0.80	100
2000	0.90	50
2200	1.00	50
2500	1.20	50
3000	1.40	50
19	0.20	500
26	0.20	500
31	0.30	500
60	0.30	400

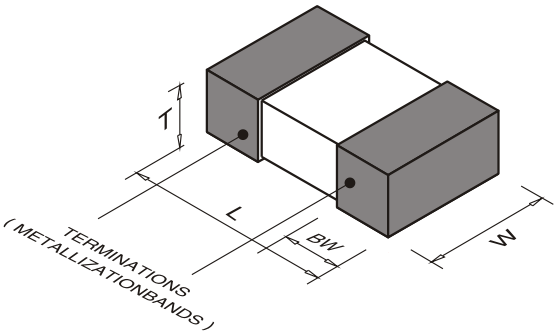
IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
70	0.30	400
80	0.30	300
100	0.30	300
120	0.30	300
150	0.30	300
180	0.35	300
220	0.30	300
300	0.30	300
500	0.30	200
600	0.30	200
800	0.30	200
1000	0.30	200
1200	0.50	100
1500	0.60	100
2000	0.60	100
2500	0.80	100
3000	1.00	80

Note:1. K=±10%,M=±20%

TECHNICAL INFORMATION

- Testing:Impedance vs.Frequency:HP 4195A
- Solderability:90% of the terminal electrode shall be covered
  Preheat:@ 260℃±5℃ for 60 seconds
  Flux:Rosin,Dip for 10 seconds ±1 second
- Thermal Shock:Impedance shall be within ±20% of initial value when temperature is –25℃ and +85℃ for 30 minutes for each 50 cycles
- Operating Temperature:–25℃ to +85℃
- Storage Temperature:–25℃ to +85℃

Note:All specifications subject to change without notice.

PHYSICAL CHARACTERISTICS

(Refer to Size Chart Page 4)